

16 (amended). A method for packaging a microelectromechanical system (MEMS) device comprising:

coating an MEMS package flexible layer with an adhesive;  
partially curing the adhesive;  
using the adhesive to attach a release sheet to the MEMS package flexible layer;  
providing a cavity having a smooth surface perimeter and extending through the release sheet, the adhesive, and at least partially through the MEMS package flexible layer;  
removing the release sheet;  
using the adhesive to attach the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity;  
providing MEMS vias through the MEMS package flexible layer extending to connection pads of the MEMS device; and  
applying a MEMS pattern of electrical conductors on the MEMS package flexible layer and extending through the MEMS vias to the connection pads.

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